www.lex.com.tw





博來科技股份有限公司

LEX COMPUTECH CO.,LTD.

Lex SYSTEM®

Product Roadmap

LEX believes your success will be our success.

2026 Q4

Contents

- LEX System Features & Advantages
- Embedded Solution Overview
- Embedded Solution Case Study
- Product Highlights
- Product Development Timeline
- Product long term supply
- Contact Information

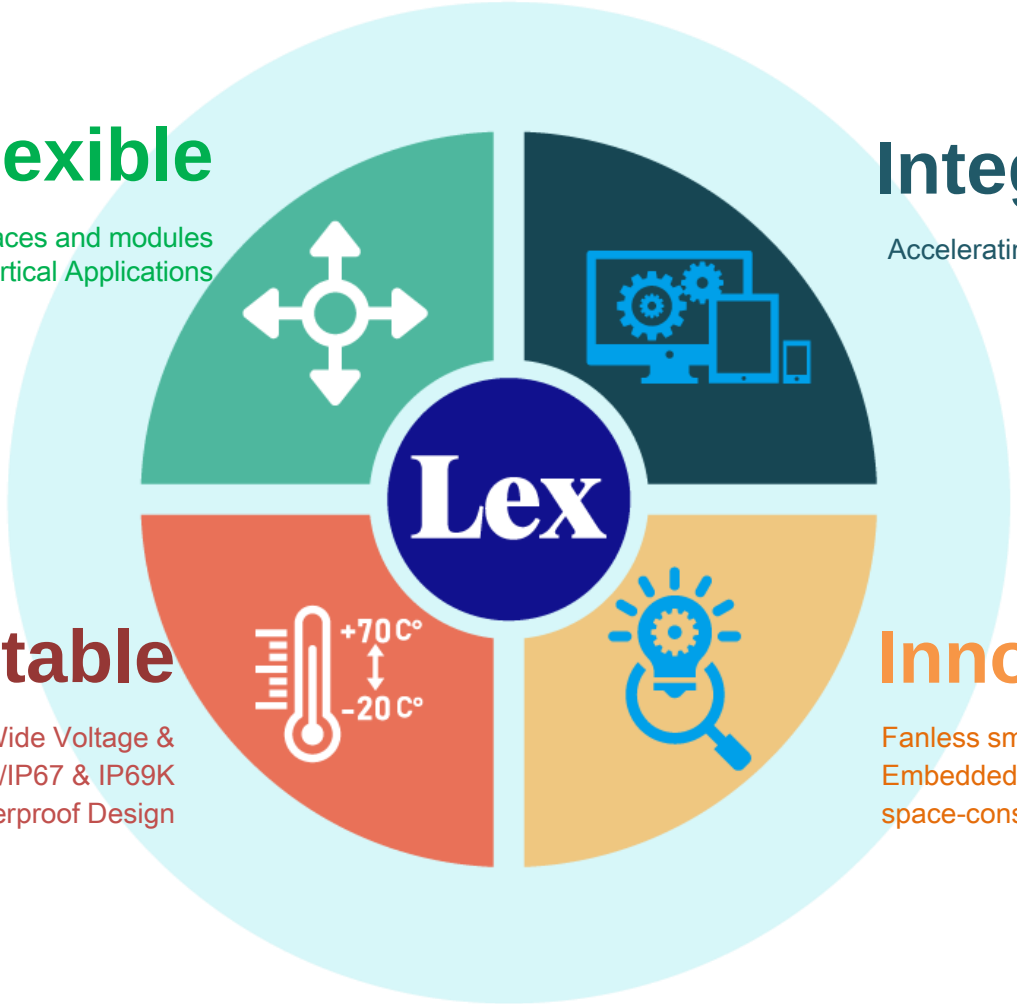
Features & Advantages

Flexible

Diverse Expansion interfaces and modules
for various Vertical Applications

Integrated

Accelerating Customer Development Speed
for Cross-Platform products



Stable

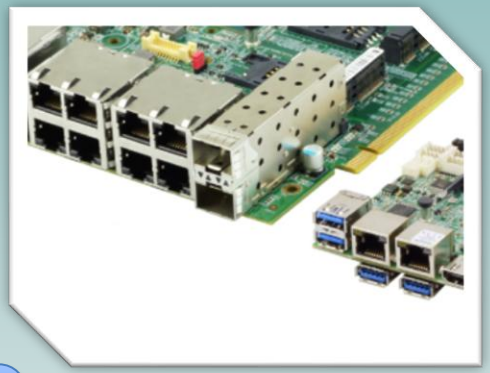
Wide Temperature, Wide Voltage &
Shock Resistance, IP66/IP67 & IP69K
Waterproof Design

Innovation

Fanless small Form Factor
Embedded tailored products or
space-constrained solutions

LEX SYSTEM – Embedded Solution

LEX offers design and manufacturing of industrial motherboards, industrial computers, expansion boards, and customized industrial computers, including edge computing systems and AI intelligent application platforms. Our in-house developed products cover four major categories:



1 Embedded IPC Board

- Single Board Computer
- CPU board
- Computer On Module
- UPS board
- ARM-based SBC



2 Customized Motherboard & Chassis

Innovating Research & Integration Services for Global OEM/ODM and System Integrators

• Applications

- Smart Manufacturing / Machine Vision
- Maritime Shipping & Navigation
- Defense / Military Robust Computers
- Smart Transportation & Railways
- IoT / IIoT
- Edge Computing Edge Gateway Control
- AI / Visual Analytics
- Smart Healthcare/ AI Medical Imaging
- Networking/ Communication Equipment

LEX SYSTEM – Embedded Solution





3 Fanless Rugged Panel PC, Fanless Embedded Systems, Servers

Fanless Rugged Panel PC

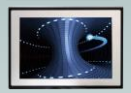


•SUPER **series** (7”/10.1”/10.4”/15”)



•VITA **series** (10.1”/15”/21.5”/23.8”)

•Slim series (8.4”/10.2”/15.1”/17”)



•SHARK IP66/67 **waterproof** (10.1”/13.3”)



•STAR IP66/67 **waterproof** (10.4”/12.1”15.1”)



•**Stainless** IP66/IP67/IP69K **waterproof** (10.4”/15.1”/19”)

Fanless Embedded System



•Rugged /Waterproof System

•In-vehicle System



•DIN Rail System

•1U server



•AI image Analysis & Machine Vision

•Ultra Compact / Compact System

4 Expansion Boards/Cards & Related Accessories

•High-Speed Ethernet Network Card / PoE / Fiber Card

•4G / 5G / WiFi / Bluetooth Module

•Video Capture Car

•USB / SIM / COM / Display Conversion Card

• M.2 / eIO Expansion Card

•Storage Card

•Digital IO Card

•Carriers and Converter Boards

•Power Boards and Charger Modules

Embedded Solution– Case Study

Smart Transportation



HAWK 3I130TW
Israel
Railway Passenger Connectivity Solution

Robotics



SKY 2 2I130DW
South Korea
Autonomous Mobile Robot



Smart Manufacturing



NET-II 2I640DW
Germany
AIoT Edge Gateway



Smart Healthcare



Rock 2I130DW
Netherlands
Medical Robotic system



2026 Q4 Product Highlights

2I160D-2.5” SBC

Intel® Core™ Ultra CPU
(Panther Lake H)
1 x HDMI ®, 1 X Type C DP ALT,
Onboard LPDDR5 16/32 GB
4 x Intel 2.5 GbE, 2 x USB 3.2, 3 x USB 2.0
2 x M.2 ,1 x Nano SIM , 1 x PCIe x2 ,
1 x USB 3.0/2.0 (SSL wafer 20 pin)
2 x MIPI-CSI, 2 x COM, 4DI / 4DO

3I160DW-3.5” SBC

Intel® Core™ Ultra CPU
(Panther Lake H)
2 x HDMI ®, LVDS or eDP (BIOS), 1 X Type C DP ALT,
2 x DDR5 SODIMM Max 96 GB
5 x Intel 2.5 GbE, 3 x USB 3.2, 5 x USB 2.0
3 x M.2 ,1 x Nano SIM ,1 x PCIex2, 2 x PCIex4
HD Audio , 3 x MIPI-CSI, 4 x COM, 4DI / 4DO

CI970D- 186 x 217 mm SBC

Intel® Core™ Ultra CPU
(Nova Lake S)
HDMI ®, DP , LVDS/eDP, 1 x Type C DP ALT,
2 x DDR5 SODIMM,
5 x Intel 2.5 GbE, 4 x USB 3.2, 4 x USB 2.0
3 x M.2 ,1 x Nano SIM, 4 x COM, 8DI / 8DO
1 x PCIe x 2 , 1 x PCIe x 4 , 1 x PCIe x 16

3I970D- 3.5 “ SBC

Intel® Core™ Ultra CPU
(Nova Lake S 35W)
HDMI ®, DP , LVDS/eDP, Type C DP ALT,
2 x DDR5 SODIMM, PCIe x 2
5 x Intel 2.5 GbE, 4 x USB 3.2, 4 x USB 2.0
3 x M.2 ,1 x Nano SIM, 2 x COM, 4DI / 4DO

2I740HW/BW
-2.5” wafer I/O SBC

Intel® ATOM Amston Lake N x7000 CPU
Onboard LPDDR5, 4GB/8GB/16GB/32GB
HDMI®, 1 x Type C DP ALT, LVDS/eDP
3 x Intel 2.5 GbE, 2 x COM
3 x USB 3.2, 2 x USB 2.0 , 2 x MIPI-CSI
2 x M.2 , 1 x Nano SIM,
Battery Charge Function (BW)

2I740PW-
Pico Express Computer on Module

Intel® ATOM Amston Lake N x7000 CPU
Onboard LPDDR5, 4GB/8GB/16GB / 32GB
HDMI®, VGA, eDP/LVDS
2 x Intel 2.5 GbE, 4 x COM, eMMC
2 x USB 3.2, 5 x USB 2.0 , Touch Screen
2 x M.2 , 1 x Nano SIM, Audio
PCIe x 2 (Pico Express I/O)

NVIDIA

2NAGX01- 2.5” Plus carrier board
For Board for Edge AI solution with
NVIDIA® Jetson Orin™ **AGX**
HDMI®, 1 x Type C DP ALT,
2 x Intel 10 GbE, 1 x GbE, 2 x COM
2 x USB 3.0, 1 x micro B USB 2.0 ,
4 x MIPI-CSI, PCIe x 2
3 x M.2 , 1 x Nano SIM, CANBus

Thor AGX
with NVIDIA® Thor™ AGX

Product Highlights（Embedded IPC Board）

intel Core 13th Gen Raptor Lake

2I130HW-2.5” Plus SBC
2I130DW-2.5” Plus SBC
2I132DW-2.5” Plus SBC
3I130DW-3.5” Plus SBC
3I130TW-161x150 mm SBC

intel Core 11th Gen Tiger Lake-UP3

2I110D-2.5” Plus SBC
2I110AW-2.5” Plus SBC
3I110HW/BW-3.5” Plus SBC

NVIDIA

2NOR01- 2.5” Plus carrier board
For Board for Edge AI solution with NVIDIA® Jetson Orin™ Nano (Super)NX

ORIN-TW
Carrier Board for Railway solution with NVIDIA® Jetson Orin™ Nano(Super) / NX

2NOR02- compact carrier board
For Edge AI solution with NVIDIA® Jetson Orin™ Nano / NX

2NOR03- compact carrier board
For Edge AI solution with NVIDIA® Jetson Orin™ Nano / NX

intel Core 10th Gen Comet Lake-S

3I470DW-155 x150 mm SBC

intel Core 9 th Gen Coffee Lake-S
intel Core 8 th Gen Coffee Lake-S

CI370D-217 x 185 mm SBC
CI371D-217 x 223 mm SBC
3I370DW-155 x130 mm SBC

intel Core 8 th Gen Whiskey Lake-U

2I810D-2.5” Plus SBC
3I810DW-3.5” Plus SBC
3I810HW/BW-3.5” Plus SBC

intel Elkhart Lake
intel Atom inside

2I640PW-Compute on Module
2I640HL-2.5”Plus SBC with Hailo-8
2I640DW-2.5”Plus SBC
2I642DW-2.5” Plus SBC
2I640CW-2.5”Plus SBC
2I640HW-2.5”Plus SBC
2I640SW-2.5”Plus SBC
3I640DW-3.5” SBC
3I640CW-3.5” SBC

NXP

2N8MP01- 2.5” Plus SBC

NXP-HAI02- -carrier board with Hailo AI chip
For Edge AiI solution with I.MX8M Plus CPU

NXP-HAI03 -carrier board with Hailo AI chip
For Edge AiI solution with I.MX8M Plus CPU

2026 Q4 Product Development timeline

Intel® Core™ Ultra CPU (Series 3)

2I160D



Intel® Core™ Ultra 300 Series (Panther Lake H) processors

Revamped I GPU and integrated NPU

Onboard LPDDR5 16/32GB

Display : 1 x HDMI®,1 x Type C DP ALT

4 x Intel 2.5 GbE LAN, 2 x USB 3.2 Gen1x1, 3 x USB 2.0,

1 x M.2 M Key, 1 x M.2 B Key, 1 x Nano SIM,

1 x PCIe x2, 1 x USB 3.0/2.0 (SSL wafer 20 pin)

2 x COM, 4DI / 4DO, 2 x MIPI-CSI,

TPM 2.0, SMBus, I2C, DC- IN : +12V

Dimension: 118 x 112 mm



HAWK 3I160DW + 12 CH GMSL

3I160DW



Intel® Core™ Ultra 300 Series (Panther Lake) processors

Revamped I GPU and integrated NPU

2 x DDR5 SODIMM, Max 128GB

Display : 2 x HDMI®, ®, LVDS or eDP (BIOS),

1 x Type C DP ALT

5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen1x1, 5 x USB 2.0,

1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM,

1 x PCIe x2, 2 x PCIe x 4

4 x COM, 4DI / 4DO, 3 x MIPI-CSI, HD Audio

TPM 2.0, SMBus, I2C, I2S, Wide Range DC-IN +9~36V

Dimension: 146 x 150 mm



HAWK 3I160DW

2026 Q4 Product Development timeline

Intel® Core™ Ultra CPU



Rock 2I140D

2I140D

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake U/H & Arrow Lake U/H)
On board LPDDR5 16/32 GB
1 x HDMI®,eDP, 4 x Intel 2.5 GbE LAN,
3 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 1 x M.2 B Key, 1 x Nano SIM
2 x COM, 4DI / 4DO, Audio (OEM)
2 x MIPI-CSI, SMBus, I2C, DC IN+ 12V
Dimension: 113 x 112 mm



3I140DW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake U/H & Arrow Lake U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, 1 x DP, LVDS or eDP (BIOS)
1 x Type C DP ALT Mode
5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe
4 x COM, 2 x CANBus , 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, I2S ,Wide Range DC IN+9~36V
Dimension: 150 x 155 mm



HAWK 3I140DW



3I140HW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake U/H & Arrow Lake U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, LVDS or eDP (BIOS)
1 x Type C DP ALT Mode
3 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, High Speed Connector (PCIe x2)
4 x COM, 2 x MIPI-CSI, 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, Wide Range DC IN+9~36V
Dimension: 146 x 150 mm



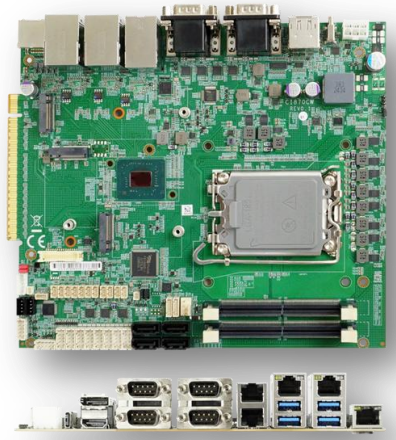
SealPro 3 3I140HW



HAWK 3I140HW+ 8 CH GMSL

2026 Q4 Product Development timeline

Intel® Core™ Ultra CPU



CI870CW

Intel® Core™ Ultra 7/5 (Arrow Lake S) Series processors
2 x DDR5 SODIMM, Max 96 GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x LVDS or eDP (BIOS), 1 x Type C DP ALT
5 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
10 x COM, 8DI / 8DO, Audio
TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)







TWISTER(L)-CI870AW

TWISTER(L)-CI870CW



CI870AW

Intel® Core™ Ultra 7/5 (Arrow Lake S) Series processors
2 x DDR5 SODIMM, Max 96GB
Multiple Independent display:
1 x HDMI®, 1 x DP,1 x Type C DP ALT
2 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 8DI / 8DO, TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)







1U Fanless-CI870AW

1U Fanless-CI870CW

2026 Q4 Product Development timeline

13th Gen Intel® Core™ Raptor Lake-P/U



2I130HW

Intel® 13th Gen Raptor Lake U/P CPU
1 x DDR5 SODIMM (Max. 32GB)
HDMI ®, eDP, LVDS
2 x Intel 2.5 GbE, 4 x USB 3.2
4 x USB 2.0 2 x COM, 4DI / 4DO,
HD Audio ,1 x Mini PCIe, 1 x M.2
108 x 102 mm



ROCK 2I130HW



IP66 IP67 Waterproof

SealPro 2I130HW





2I130DW / 2I132DW



FOX 2I130DW



SKY 2 2I130DW

Intel® 13th Gen Raptor Lake U CPU
1 x DDR5 SODIMM (Max. 32GB) -2I130DW
Onboard LPDDR5 16/ 32GB-2I132DW
HDMI ®, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2 , 1 x Nano SIM
108 x 102/ 108 x 105 mm



ROCK 2I130DW



3I130DW

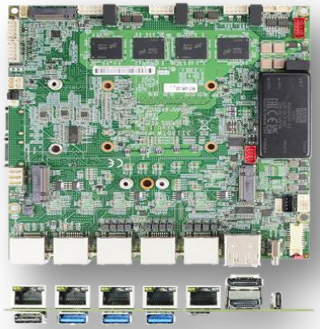
Intel® 13th Gen Raptor Lake P / U CPU
2 x DDR5 SODIMM (Max. 64GB)
2 x HDMI ®,eDP , 1 x Type C DP ALT Mode
5 x Intel 2.5 GbE, 3 x USB 3.2, 5x USB 2.0
1 x Mini PCIe, 2 x M.2 ,1 x Nano SIM
2 x COM, 4DI / 4DO
146 x 110 mm



HAWK 3I130DW



SKY 3 3I130DW



3I130TW

Intel® 13th Gen Raptor Lake- U CPU
On-board LPDDR5 (16GB/32 GB)
HDMI ®,DP, eDP ,5 x Intel 2.5 GbE,
3 x USB 3.2, 3x USB 2.0, 3 x M.2 ,
1 x Nano SIM ,2 x ISO-COM, HD Audio
2 x ISO- CANBus, 4DI / 4DO , onboard NVMe
CPC –Ignition Delay on/off control
161 x 150 mm

EN50155



HAWK 3I130TW (M12)



Mobile Rack (Optional)

2026 Q4 Product Development timeline

NVIDIA Jetson Orin Nano(Super)/ NX SOM Carrier Board

JETSON Orin™ NX | JETSON Orin™ Nano | NVIDIA

CPU Board:
NVIDIA Jetson NX: 8 / 16GB LPDDR5, 70 / 100 TOPs
NVIDIA Jetson Nano(Super): 4 / 8GB LPDDR5, 20 / 40 TOPs
AI Accelerator: NVIDIA® Jetson Orin™ Nano(Super) / Orin™ NX

2NOR02

1 x HDMI®, 1 x GbE
8 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
1 x RS232 (OEM to RS422)
1 x M.2 M key, 1 x M.2 B key, URAT, I2S, 2 x I2C





FOX 2NOR02

ORIN-TW

1 x DP, 5 x GbE (1 + 4 x PoE)
1 x USB 3.1 Type C ; 2 x USB 3.1 Type A ; 1x USB 2.0
Mic-in / Line-out ; AMP 2W, 2 x SATA
2 x Isolated RS232 / RS422 / RS485, 1 x Isolated CANBus
1 x M.2 M key, 4 x M.2 B key, 1 x M.2 E Key, 1 x Nano SIM
2 x MIPI CSI, SPI, I²S, 3 x I²C,8DI / 8 DO,
ISO Wide Range +9~36V, CPC-Ignition on/off delay control



EN50155



HAWK ORIN-TW
M12 I/O / Mobile Rack (Optional)

2NOR03

1 x HDMI ®, 1 x GbE, 1 x 2.5GbE
2 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG)
1 x RS232 (OEM Option RS422)
1 x M.2 M key, 1 x M.2 B key
Support **8 X GMSL cameras**





FOX 2NOR03+GM04

2NOR01

1 x HDMI®, , 2 x 2.5GbE, 1 x GbE
4 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
Mic-in / Line-out ; AMP 2W
2 x RS232 (Option RS422), 1 x CANBus
1 x M.2 M key 2 x M.2 B key, 1 x SIM, 4DI / 4DO
Internal wafer: SPI, I2S, I2C, USB 2.0





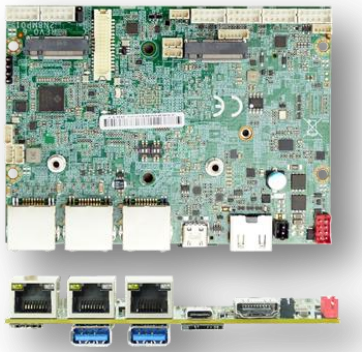
SKY 2 2NOR01



ROCK 2NOR01

2026 Q4 Product Development timeline

NXP i.MX8M Plus /ARM Cortex-A53



2N8MP01

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 + M7 CPU
LPDDR4, 4GB / 8GB
Independent display: 1 x HDMI ®, LVDS,
3 x GbE LAN, 2 x USB 3.0, 3 x USB 2.0
2 x COM, 3 x M.2, 1 x Nano SIM, 1 x Type C USB 3.0 (OTG)
4DI / 4DO,1 x MIPI (CSI),1 x CANBus
115.4 x 84.5 mm



NET-II 2N8MP01



PALM-NEX001

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 CPU
LPDDR4, 8GB (NEX-8MP)
32GB eMMC 5.1 (NEX-8MP),
expandable to 256GB
HDMI ® ; 2 x GbE ; 2 x USB 3.0 / 2.0
1 x Micro SD, 1 x RS232, 1 x RS485
DC input : +5V
71.4W x 71.4D x 29.5H mm

Ultra Compact solution with Onboard Hailo-8™ AI processor

EMPOWERED BY HAILO

NXP-HAI02 / HAI03

NXP i.MX8M Plus (Quad core) ARM Cortex-A53 CPU
LPDDR4, 8GB (NEX-8MP),32-256GB eMMC 5.1 (NEX-8MP)
Mini HDMI ®, 1 x USB 3.0 Type C,1 x GbE(M12) or 2 x RJ45 ;
1 x USB 3.0 Type A, 1 x Micro SD,
M8 Connector: DC Power, LAN, DI/DO ,RS485
Wide Range DC-IN +9-24V
Dimension: 66W x 94D x 30.8H mm



NXP-HAI02 NXP-HAI03

With NEX-8MP computer on module



MINI NXP-HAI02



MINI NXP-HAI03

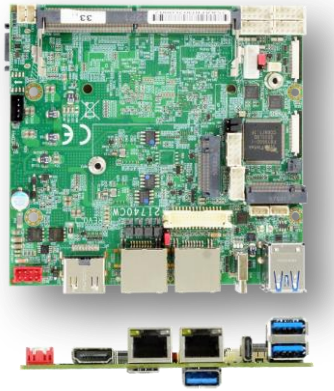
2026 Q4 Product Development timeline

Intel® Amston Lake ATOM x7000 series processor



2I740DW

Intel® ATOM Amston Lake x7000 series CPU
Onboard LPDDR5, Max 32GB
HDMI® ,3 x Intel 2.5 GbE,
3 x USB 3.2, 2 x USB 2.0
2 x M.2 , 1 x Nano SIM, 2 x COM,
Wide Range DC-IN +9~24V
115.4 x 84.5 mm



2I740CW

Intel® ATOM Amston Lake x7000 series CPU
1 x DDR5 SODIMM, Max. 16GB
HDMI®, Type C ALT, 1 x LVDS or eDP (BIOS)
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB3.2 Type C , 2 x MIPI-CSI, 4DI/4DO
2 x M.2 , 4 x COM, Wide Range DC-IN +9~36V
108 x 102 mm



2I740AW

Intel® ATOM Amston Lake x7000 series CPU
Onboard LPDDR5, Max 32GB
eMMC 5.1 32GB ~ 256GB
HDMI® ,1 x USB 3.2 Type C DP ALT,
1 x Intel 2.5 GbE,4 x USB 3.2, 1 x USB 2.0
2 x M.2 , 1 x Nano SIM, 4 x COM,
Wide Range DC-IN +9~24V
117 x 98.2 mm



NET-II 2I740DW



FOX 2I740DW



FOX 2I740CW
FOX 2I740CW



LEX Sereies Pancel PC



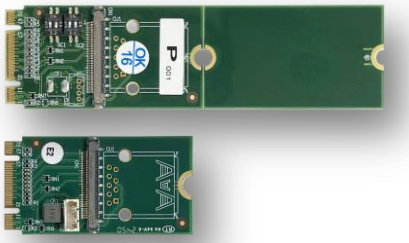


TERA 2I740AW

TERA 2I740AW
Front

2026 Q4 Product Development timeline

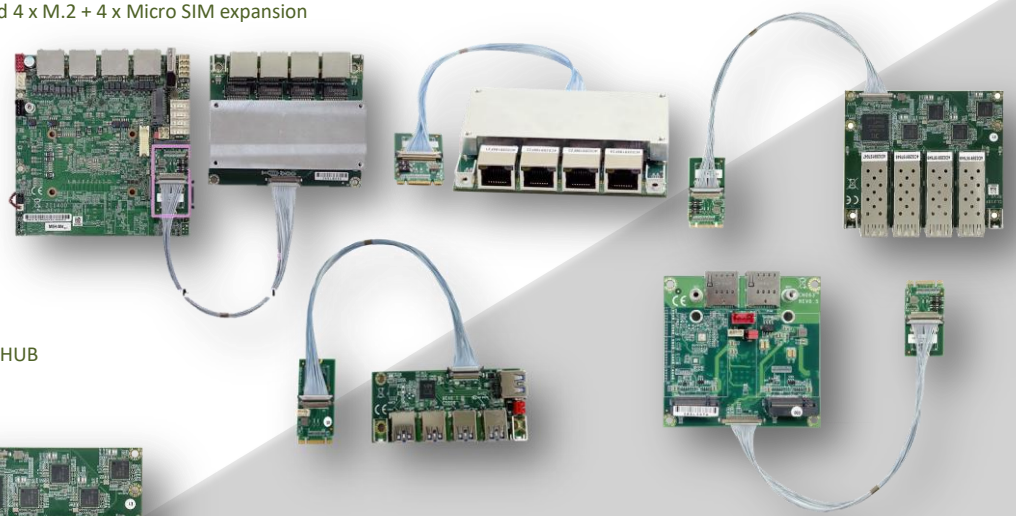
Expansion Card and Modules



CN073 / CN075

M.2 B+M Key 2242 /2280 to USB 3.0 / PCIe converter board

Easy Expansion:
Connect the set to the SBC's M.2 B+M slot to enable 4 x GbE LAN / 4 x PoE LAN / 4 x Fiber Lan / 4 x USB 3.0 and 4 x M.2 + 4 x Micro SIM expansion





CU006
1 x USB convert to 4 x USB 3.0 HUB



CL210A
4 Port GbE LAN board



CL210P
4 Port PoE GbE LAN



CL210F
4 Port Fiber LAN board

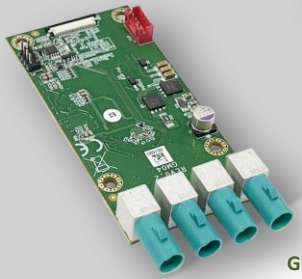


Top

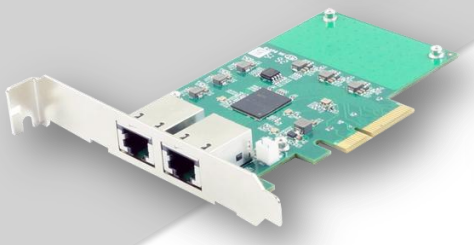


Bottom

CN063
4 x M.2 + 4 x Micro SIM



GM04
4 CH GMSL input (MIPI-CSI)



E610A
2 x 10 GbE LAN – PCIe Card



ADC002
Analog I/O Board

LEX SYSTEM with Long-Term Supply

EOL Timeline	2026	2027	2028	2030	2031	2032	2033	2034	2035	2036
Bay Trail		Q4								
Apollo Lake	Q4									
Elkhart Lake					Q1					
Amston Lake								Q2		
Skylake 6th	Q2									
Kaby Lake 7th	Q2									
Coffee Lake 8th			Q3							
Coffee Lake 9th			Q3							
Whisky Lake			Q3							
Comet Lake				Q2						
Tiger Lake UP3				Q3						
Raptor Lake							Q1			
Meteor Lake-U/H							Q4			
Arrow Lake-U				Q1						
Arrow Lake-S				Q1						
Panther Lake										Q1
Nova Lake										Q1
i.MAX 8M Plus									Q1	
Jetson Orin Nano NX				Q1						

* Product life span in alignment with Intel's IOTG / NVIDIA modules Life cycle /NXP CPU longevity.

Contact us

LEXCOM B.V.
(The Netherlands)

Tel:+31-73-6872390
Fax:+31-73-6872398
Email: info@lex.com.tw

LEX COMPUTECH CO.,LTD.
(Taiwan Taipei)

Tel:+886-2-2228-1055
Fax:+886-2-2228-1056
Email: lex.sales@lex.com.tw

LEX COMPUTECH CO.,LTD.
(South Korea)

Tel:+ 82-10-5936-4669
Email: yeon@lex.com.tw

CHINA Subsidiary
研毅通电子科技有限公司

Tel:+86-0512-65993318
+86 18500172031

E-mail: robin@yanyitong.com.cn